I wte-terence Text Search

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4739	(flex\$5 and silicon).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 11:05
L2	3756	(flexible and silicon).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 11:06
L3	3756	(flexible and silicon).clm.	US-PGPUB; USPAT	OR	OFF	2006/05/30 11:08
L4	534469	(groove trench slot slit gutter trough furrow ditch).clm.	US-PGPUB; USPAT	OR	ON	2006/05/30 11:11
L5	376	(flexible and silicon near substrate). clm.	US-PGPUB; USPAT	OR	OFF	2006/05/30 11:08
L6	77	4 and 5	US-PGPUB; USPAT	OR	OFF	2006/05/30 11:08
L7		1 and 6	US-PGPUB; USPAT	OR	OFF	2006/05/30 11:09
L8	404206	(surface top bottom face plane planar).clm. and (groove trench slot slit gutter trough furrow ditch).clm.	US-PGPUB; USPAT	OR	ON	2006/05/30 11:14
L9	61	7 and 8	US-PGPUB; USPAT	OR	ON	2006/05/30 11:14
L10	136547	(surface top bottom face plane planar).clm. near3 (groove trench slot slit gutter trough furrow ditch). clm.	US-PGPUB; USPAT	OR	ON .	2006/05/30 11:14
L11	29	7 and 10	US-PGPUB; USPAT	OR	ON	2006/05/30 11:14

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	21	("5808198" or "5490421" or "3860949" or "4984063") and flex\$5 and silicon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:00
L2	2	("5808198" or "5490421" or "3860949" or "4984063") and flex\$5 and silicon and @pd>"20051130"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:00
L3	1	(US-20040070053-\$).did.	US-PGPUB	OR	OFF	2006/05/30 10:00
L4	1	L3 and flexible	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:00
*L5	1	silicon adj substrate and vibration adj sensor and groove and @pd>"20051130"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON The second	2006/05/30 10:04
L6	192	(257/668,669,674,738).CCLS. and @pd>"20051130"	US-PGPUB; USPAT	OR	OFF	2006/05/30 10:05
L7	10	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic and @pd>"20051130"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:06
L8	3	("5531002" or "5406848" or "5421213") and @pd>"20051130"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/05/30 10:06
L9	1	flexible adj silicon adj substrate and @pd>"20051130"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:07

L16	146	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:08
		"4533100" "4590801").PN.	wa 1			
		"4457173" "4462254" "4483194" "4510802" "4512192"	The state of the s		1.	
4 1		"4345474" "4445376"	April 20		**	
		"4281384" "4311046" "4342227"		and the second of the second o	7,72	
		"4221131" "4258577"				
		"4104920" "4155257" "4199990"				
		"3902374" "3924475" "4009607" "4056163" "4091679"			the first	
	ar jo	"3897690" "3897997" "3003374" "3034475"			Tay be as	
- 10 c		"3813505" "3842681" "3859847"			a Para di	
w .		"3739202" "3744322"				
		"3572089" "3710629" "3713088"	USUCK			
w		"2793028" "2947067" "3226981" "3382724" "3382726"	USPAT; USOCR	Promit to the second se		
L15	47	("2544646" "2767973"	US-PGPUB;	OR	OFF	2006/05/30 10:08
	اع <u>د</u> ن و	"5421213"	USPAT; USOCR; EPO; JPO; IBM_TDB	n ya kama a wa wa	a lo	⊀া আ≾ুয়েও ড
L14	59	"5531002" or "5406848" or	US-PGPUB;	OR	OFF	2006/05/30 10:08
L13	1	(US-20040070053-\$).did.	US-PGPUB	OR	OFF	2006/05/30 10:08
L12	0	L10 and @pd>"20051130"	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/30 10:08
	, 4, 4, 4, 4, 4, 4, 4, 4, 4, 4, 4, 4, 4,	L10 and silicon and @pd>"20051130"	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/30 10:08
Ľ11	:. ii	"3739202" "3744322" "3813505" "3842681" "3859847" "3897690" "3897997" "3902374" "3924475" "4009607" "4056163" "4091679" "4104920" "4155257" "4199990" "4221131" "4258577" "4281384" "4311046" "4342227" "4345474" "4445376" "4457173" "4462254" "4483194" "4510802" "4512192" "4533100" "4590801").PN.				
L10	47	("2544646" "2767973" "2793028" "2947067" "3226981" "3382724" "3382726" "3572089" "3710629" "3713088"	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/30 10:07

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L17	1902	((bend bending bended) and silicon and (groove trench) and (bond bonded bonding)) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:08
L18	9482	(bend bending bended) and silicon and (groove trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:08
L19	5258	(bend bending bended) and silicon and (groove trench) and (bond bonded bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:08
L20	1	L3 and (flexible or curv\$3 or bent or	US-PGPUB;	OR	OFF	2006/05/30 10:08
*		bending)	USPAT; EPO;	· .		
	4		DERWENT; IBM_TDB			
L21	1	(US-5531002-\$).did.	USPAT	OR	OFF	2006/05/30 10:08
L22	1	L21 and flexible adj substrate	US-PGPUB;	OR	ON	2006/05/30 10:08
-,			USPAT; EPO;			
	# 10 m		DERWENT; IBM_TDB	4		
L23	1	L21 and flexible adj substrate same silicon	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/30 10:08
L24	1	L21 and flexible adj substrate same	US-PGPUB;	OR	ON	2006/05/30 10:08
		thickness	USPAT; EPO;			
	- i		DERWENT; - IBM_TDB			
L25	1	L21 and groove	US-PGPUB;	OR	ON	2006/05/30 10:08
		_	USPAT; EPO; DERWENT; IBM_TDB			2000
L26	1	L21 and groove with thin	US-PGPUB;	OR	ON	2006/05/30 10:08
X			USPAT; EPO;	90.		(F)
			DERWENT; IBM_TDB			
L27	1	(US-20040070053-\$).did.	US-PGPUB	OR	OFF	2006/05/30 10:08

L28	1	L27 and groove with thin	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/30 10:08
L29		L27 and groove	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/30 10:08
L30	36	12345789	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/30 10:10